IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re Application of

Daisuke Nakamura et al :

Filed: Herewith :

For: HEAT DISSIPATING STRUCTURE OF PRINTED

CIRCUIT BOARD AND FABRICATING METHOD THEREOF

Director

U.S. Patent and Trademark Office

P.O. Box 1450

Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

Applicants submit herewith a reference of which they are aware, which they believe may be material to the examination of this application and which they may have a duty to disclose in accordance with 37 CFR 1.56.

While this Information Disclosure Statement may be "material" pursuant to 37 CFR 1.56, it is not intended to constitute an admission that any document referred to herein is "prior art" for this invention unless specifically designated as such.

FILING OF PAPERS AND FEES BY "EXPRESS MAIL" WITH CERTIFICATE IN ACCORDANCE WITH 37 CFR 1.10

I hereby certify that this correspondence is being deposited with the United States Postal Service on the date shown below with sufficient postage as "Express Mail" in an envelope with Mailing Label No. EV303712989US placed thereon prior to mailing and addressed to the Director, U.S. Patent and Trademark Office, P.O. Box 1450, Alexandria, VA 22313-1450.

Margery B. Hood

Dated: November 25 2003

In accordance with 37 CFR 1.97(g), the filing of this Information Disclosure Statement should not be construed to mean that a search has been made or that no other material information as defined under 37 CFR 1.56(a) exists.

The enclosed reference is cited in the specification. Also enclosed is a Form PTO-1449 listing the cited reference.

Respectfully submitted,

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November 24, 2003
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